Listing of Claims:

1. (Currently Amended) A solid electrolytic capacitor comprising:

a lead wire;

an anode member ~~formed by~~ comprising a sintered member of a valve-action metal powder ~~and embedded therein~~ having the lead wire embedded therein;

a dielectric layer formed on a surface of the anode member;

a first electrolyte ~~layer~~ element in an electrolyte layer formed on the dielectric layer and defining a plurality of cavities;

non-conductive particles dispersed in the cavities defined by the first electrolyte element;

a second electrolyte element provided in the electrolyte layer so as to surround the non-conductive particles;

a cathode member formed on the first electrolyte layer such that particles of a material of the cathode member are dispersed in the electrolyte layer;

a silver paste layer formed on the cathode member;

external terminals respectively connected to the lead wire and the silver paste layer; and

a resin package molded so as to expose the external terminals. ~~, in which the first electrolyte layer includes particles constituting the cathode member,~~

~~said solid electrolytic capacitor further comprising non-conductive particles between the dielectric layer and the cathode member except of the first electrolyte layer, and a second electrolyte layer formed between the dielectric layer and the cathode member, wherein the second electrolyte layer is formed so as to contain the non-conductive particles.~~

2. (Currently Amended) A solid electrolytic capacitor ~~according to claim 1,~~ comprising:

a lead wire;

an anode member comprising a sintered member of a valve-action metal powder having the lead wire embedded therein;

a dielectric layer formed on a surface of the anode member;

a first electrolyte element in an electrolyte layer formed on the dielectric layer and defining a plurality of cavities;

non-conductive particles dispersed in the cavities defined by the first electrolyte element;

a second electrolyte element provided in the electrolyte layer so as to surround the non-conductive particles;

a cathode member formed on the electrolyte layer such that particles of a material of the cathode member are dispersed in the electrolyte layer;

a silver paste layer formed on the cathode member; and

external terminals respectively connected to the lead wire and the silver paste layer;

wherein [[:]] the non-conductive particles are also positioned in an area defined by a recess in the dielectric layer, and said second electrolyte ~~layer~~ element is ~~formed~~ provided in the electrolyte layer after said non-conductive particles are positioned in ~~an~~ the area ~~constituting a~~ defined by the recess ~~on~~ in said dielectric layer.

3. (Currently Amended) A solid electrolytic capacitor ~~according to claim 1,~~ comprising:

a lead wire;

an anode member comprising a sintered member of a valve-action metal powder having the lead wire embedded therein;

a dielectric layer formed on a surface of the anode member;

a first electrolyte element in an electrolyte layer formed on the dielectric layer and defining a plurality of cavities;

non-conductive particles dispersed in the cavities defined by the first electrolyte element;

a second electrolyte element provided in the electrolyte layer so as to surround the non-conductive particles;

a cathode member formed on the electrolyte layer such that particles of a material of the cathode member are dispersed in the electrolyte layer;

a silver paste layer formed on the cathode member; and external terminals respectively connected to the lead wire and the silver paste layer;

wherein said second electrolyte ~~layer~~ element is ~~formed~~ provided in the electrolyte layer after said non-conductive particles are positioned; and ~~in such a continuous manner that~~ wherein a distance from an interface between said ~~first~~ electrolyte layer and said dielectric layer to a surface of said anode member is smaller than an ~~averaged~~ average thickness of said ~~first~~ electrolyte layer.

4. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 2, wherein said non-conductive particles are also positioned on ~~the~~ a surface of said dielectric layer ~~and in said first electrolyte layer~~, and said second electrolyte element ~~layer being formed, whereby~~ is provided so as to prevent said cathode member ~~and~~ from contacting said non-conductive particles ~~are not in a direct contact~~.

5. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said non-conductive particles have an ~~averaged~~ average size which is smaller than an ~~averaged~~ average size of the particles ~~constituting~~ of the material of said cathode member.

6. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said valve action metal is ~~any~~ one of Nb, Al, Ta, Ti, Hf and Zr.

7. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said first electrolyte ~~layer~~ element includes at least one of a conductive ~~polymers~~ polymer formed by polymerizing ~~at least one of~~ pyrrole [[,]] and a conductive polymer formed by polymerizing thiophene ~~and derivatives thereof~~.

8. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 7, wherein said ~~first~~ electrolyte layer includes a conductive powder ~~constituted by~~ comprising at least one of SnO_2 powder, ~~and~~ ZnO powder, ~~or~~ and a carbon-based conductive filler ~~constituted by~~ comprising at least one of carbon black, graphite and carbon fibers.

9. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 8, wherein said conductive powder ~~is covered by~~ comprises the at least one of the SnO_2 powder and the ZnO powder covering at least ~~either~~ one of TiO_2 and ~~$BaSo_4$~~ $BaSO_4$.

10. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 7, wherein said ~~first~~ electrolyte layer includes a carbon-based conductive filler ~~constituted by~~ comprising at least one of carbon black, graphite and carbon fibers.

11. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said second electrolyte ~~layer~~ element ~~is formed by presence of a~~ comprises a conductive polymer ~~including~~ which surrounds the non-conductive particles, and wherein said second electrolyte element is provided between (i) a surface of at least one of said dielectric layer ~~or~~ and said cathode member, and (ii) ~~graphite~~ the particles of the material of the cathode member which are dispersed in the electrolyte layer.

12. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said cathode member ~~is formed by~~ comprises graphite.

12. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 1, wherein said cathode member ~~is formed by~~ comprises graphite.

13. (Currently Amended) A method of producing a solid electrolytic capacitor, said method comprising ~~the steps of~~:

sintering a valve-action metal powder while embedding a lead wire therein to form an anode member;

forming a dielectric layer on a surface of said anode member;

forming ~~a first~~ an electrolyte layer, including a first electrolyte element, on said dielectric layer of said anode member;

immersing said anode member having the ~~first~~ electrolyte layer formed thereon in a colloid solution in which non-conductive colloid particles are dispersed, ~~followed by~~ and then drying said anode member;

~~forming~~ providing a second electrolyte element in the electrolyte layer; ~~and~~

forming a cathode member so as to sandwich said ~~first~~ electrolyte layer ~~and said second electrolyte layer with~~ between said cathode layer and said dielectric layer,

~~then~~ forming a silver paste layer on said cathode member, and ~~then~~

connecting external terminals respectively with said lead wire and said silver paste layer and applying a resin mold so as to expose said external terminals.

14. (Currently Amended) The method according to claim 13, wherein said immersion ~~step~~ of the anode member in the colloid solution causes the non-conductive particles to be present between said dielectric layer and said first electrolyte element ~~layer~~.

15. (Currently Amended) The method according to claim 13, wherein said immersion ~~step~~ of the anode member in the colloid solution causes the non-conductive particles to be present in an area ~~constituting~~ defined by a recess on ~~the~~ a surface of said dielectric layer.

16. (Currently Amended) The method according to claim 13, wherein said immersion ~~step~~ is carried out under a ~~reduced~~ pressure ~~, and causes~~ such that the non-conductive particles ~~to be~~ are present in an area on ~~the~~ a surface of said dielectric layer where a distance from an interface between said first electrolyte layer and said dielectric layer to ~~the~~ a surface of said anode member is smaller than an ~~averaged~~ average thickness of said dielectric layer.

17. (Currently Amended) The method according to claim 13, wherein said non-conductive particles have an ~~averaged~~ average size which is smaller than an ~~averaged~~ average size of particles ~~constituting~~ of a material of said cathode member.

18. (Currently Amended) The method according to claim 13, wherein ~~in~~ at least one of ~~the steps of forming~~ said first electrolyte elment and said second electrolyte ~~layers,~~ element comprise at least one of a conductive ~~polymers, use is made of at least one of~~ polymer polymerized from pyrrole, and a conductive ~~polymers~~ polymer polymerized from ~~at least one of pyrrole,~~ thiophene ~~, and derivatives thereof~~.

19. (Currently Amended) ~~A~~ The solid electrolytic capacitor according to claim 3, wherein said non-conductive particles are also positioned on ~~the~~ a surface of said dielectric layer ~~and in said first electrolyte layer~~, and said second electrolyte element ~~layer being formed, whereby~~ is provided so as to prevent said cathode member ~~and~~ from contacting said non-conductive particles ~~are not in a direct contact~~.